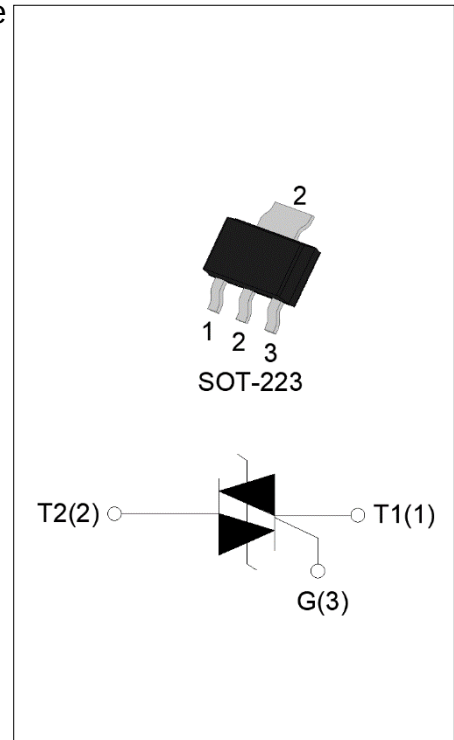


ACJT01V-1000TW 1A TRIAC

Rev.A.1.1

DESCRIPTION:

The ACJT01V-1000TW triac is suitable for general purpose AC switching. It can be used as an ON/OFF function in applications such as heating regulation, induction motor starting circuits, for phase control operation in light dimmers, motor speed controllers. The ACJT01V-1000TW embeds a TVS structure to absorb the inductive turn-off energy such as those described in the IEC 61000-4-5 standards. Package SOT-223 is RoHS compliant.


MAIN FEATURES

Symbol	Value	Unit
$I_{T(RMS)}$	1	A
V_{DRM}/V_{RRM}	1000	V
$I_{GT\ I/II/III}$	5/5/5	mA

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Storage junction temperature range	T_{stg}	-40-150	°C
Operating junction temperature range	T_j	-40-125	°C
Repetitive peak off-state voltage ($T_j=25^{\circ}C$)	V_{DRM}	1000	V
Repetitive peak reverse voltage ($T_j=25^{\circ}C$)	V_{RRM}	1000	V
RMS on-state current ($T_c \leq 89^{\circ}C$)	$I_{T(RMS)}$	1	A
Non repetitive surge peak on-state current (full cycle , $t_p=20ms$, $T_j=25^{\circ}C$)	I_{TSM}	15	A
Non repetitive surge peak on-state current (full cycle , $t_p=16.6ms$, $T_j=25^{\circ}C$)		16.5	
I^2t value for fusing ($t_p=10ms$, $T_j=25^{\circ}C$)	I^2t	1.25	A ² s
Critical rate of rise of on-state current ($I_G=2 \times I_{GT}$, $f=100Hz$, $T_j=125^{\circ}C$)	di/dt	50	A/ μs
Peak gate current ($t_p=20\mu s$, $T_j=125^{\circ}C$)	I_{GM}	2	A
Average gate power dissipation ($T_j=125^{\circ}C$)	$P_{G(AV)}$	0.1	W
Peak gate power	P_{GM}	5	W

Peak pulse voltage ($T_j=25^{\circ}\text{C}$; non-repetitive, off-state; FIG.8)	V_{pp}	3.75	kV
--	----------	------	----

ELECTRICAL CHARACTERISTICS ($T_j=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Test Condition	Quadrant	Value		Unit
I_{GT}	$V_D=12\text{V}$ $R_L=33\Omega$	I - II - III	MAX.	5	mA
V_{GT}		I - II - III	MAX.	1	V
V_{GD}	$V_D=V_{DRM}$ $T_j=125^{\circ}\text{C}$ $R_L=3.3\text{k}\Omega$	I - II - III	MIN.	0.2	V
I_L	$I_G=1.2I_{GT}$	I - III	MAX.	10	mA
		II		20	
I_H	$I_T=100\text{mA}$		MAX.	10	mA
dV/dt	$V_D=670\text{V}$ Gate Open $T_j=125^{\circ}\text{C}$		MIN.	550	V/ μs
$(dI/dt)_c$	$(dV/dt)_c=10\text{V}/\mu\text{s}$, $T_j=125^{\circ}\text{C}$		MIN.	0.6	A/ms
t_{on}	$I_G=10\text{mA}$ $I_A=200\text{mA}$ $I_R=20\text{mA}$ $T_j=25^{\circ}\text{C}$		TYP.	2	μs
t_{off}				20	
V_{CL}	$I_{CL}=0.1\text{mA}$ $t_p=1\text{ms}$		MIN.	1050	V

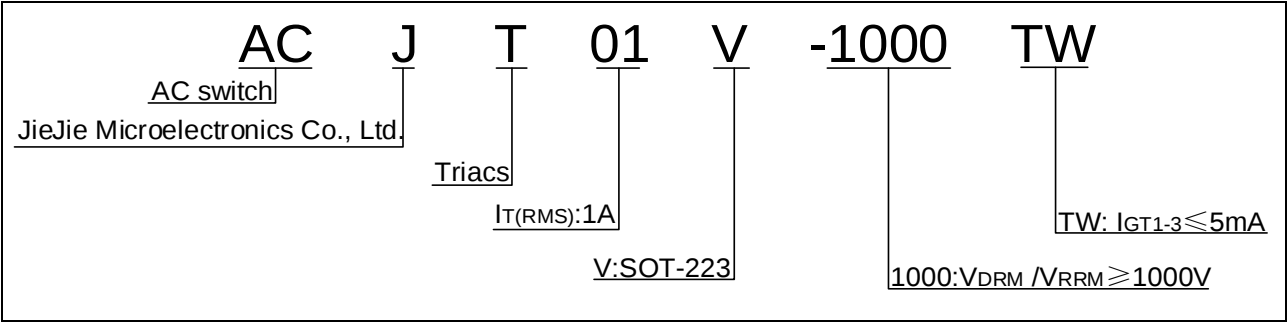
STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX.)	Unit
V_{TM}	$I_{TM}=1.1\text{A}$ $t_p=380\mu\text{s}$	$T_j=25^{\circ}\text{C}$	1.45	V
V_{TO}	Threshold voltage	$T_j=125^{\circ}\text{C}$	0.98	V
R_D	Dynamic resistance	$T_j=125^{\circ}\text{C}$	181	$\text{m}\Omega$
I_{DRM}	$V_D=V_{DRM}$ $V_R=V_{RRM}$	$T_j=25^{\circ}\text{C}$	8	μA
I_{RRM}		$T_j=125^{\circ}\text{C}$	0.4	mA

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	junction to case (AC)	25	$^{\circ}\text{C}/\text{W}$
$R_{th(j-a)}$	junction to ambient (AC)	140	$^{\circ}\text{C}/\text{W}$

ORDERING INFORMATION



MARKING

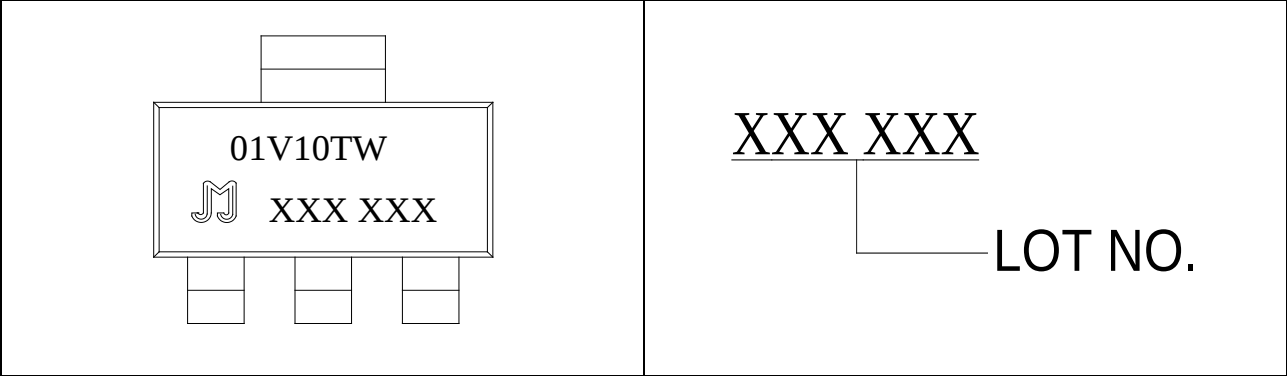


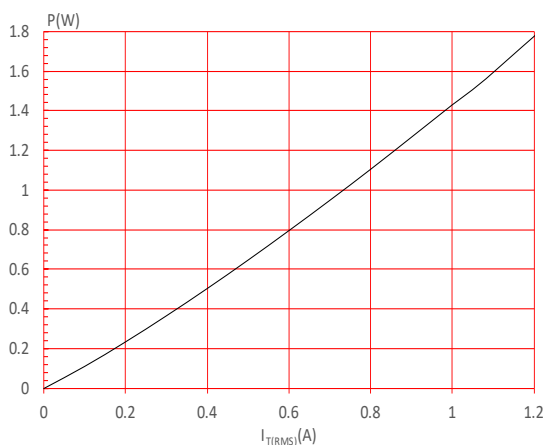
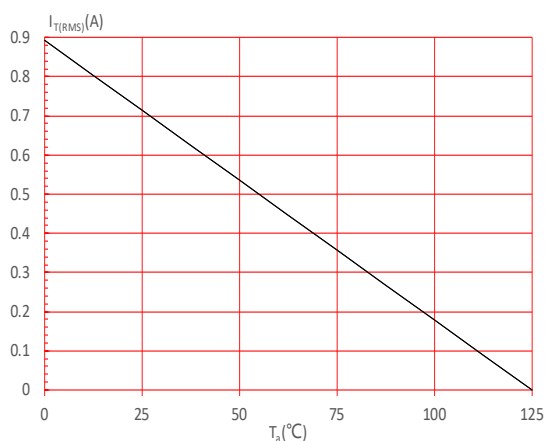
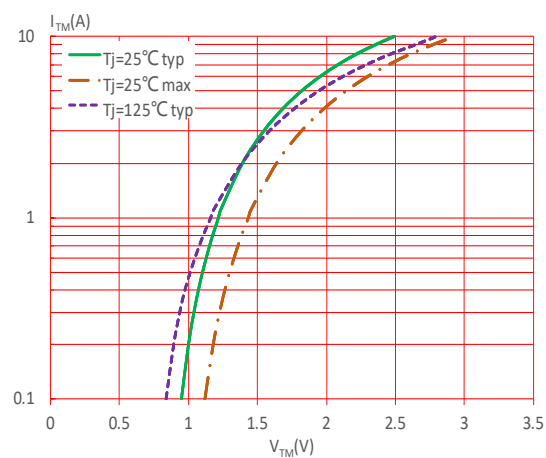
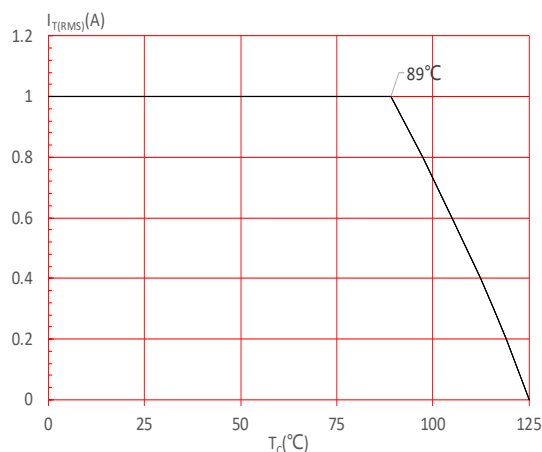
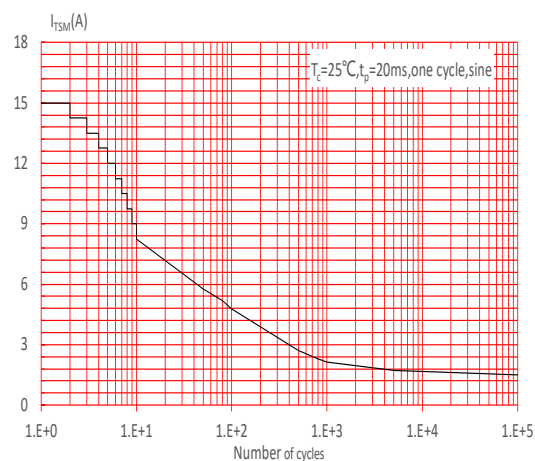
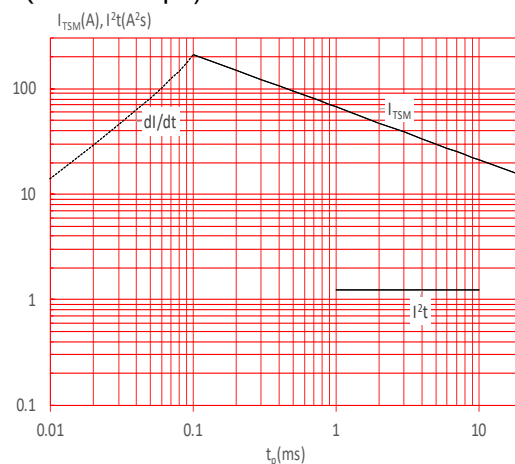
FIG.1: Maximum power dissipation versus RMS on-state current

FIG.3: RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness: 35 μ m) (full cycle)

FIG.5: On-state characteristics

FIG.2: RMS on-state current versus case temperature

FIG.4: Surge peak on-state current versus number of cycles

FIG.6: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 20ms$, and corresponding value of I^2t ($dl/dt < 50A/\mu s$)


FIG.7: Relative variations of gate trigger current, holding current and latching current versus junction temperature

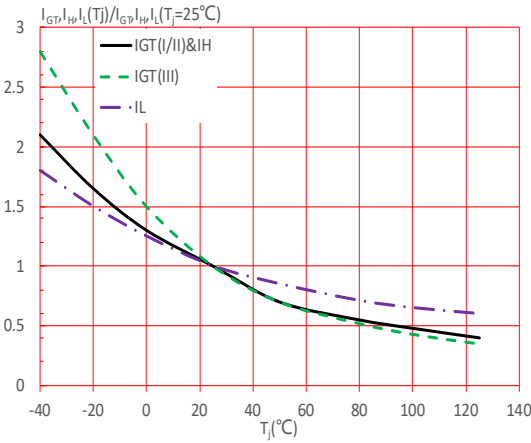
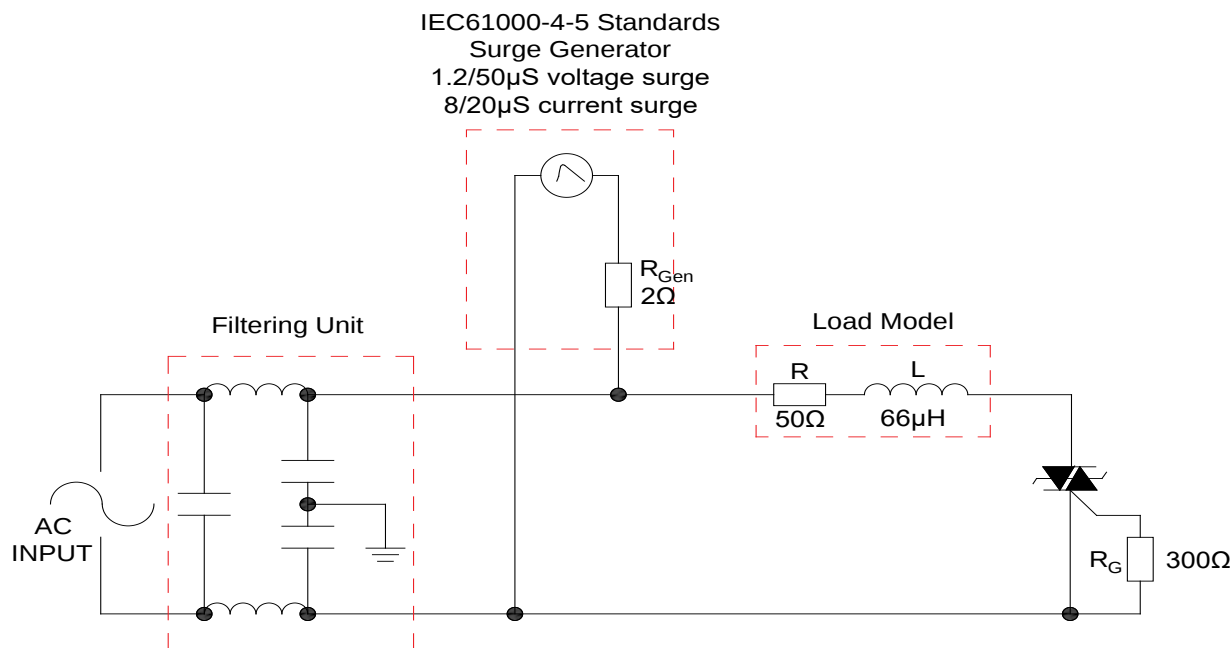
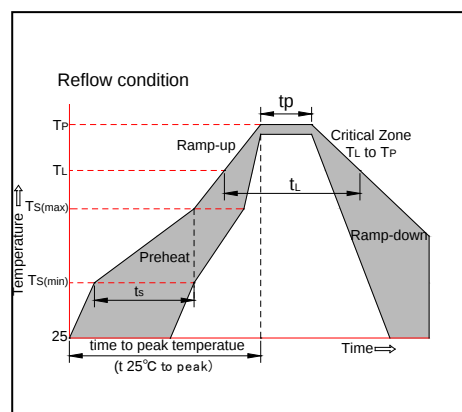


FIG.8: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards



SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquidus)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C



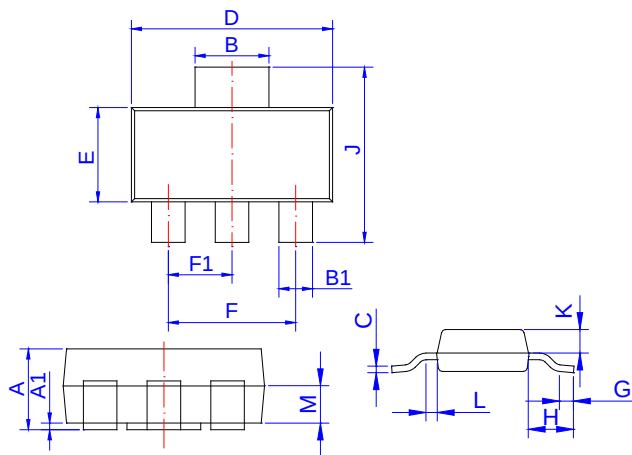
ORDERING INFORMATION

Order code	Voltage $V_{\text{DRM}}/V_{\text{RRM}}$ (V)	IGT(mA)	Package	Base qty. (pcs)	Delivery mode
ACJT01V-1000TW	1000	5	SOT-223	4,000	Tape & Reel

Document Revision History

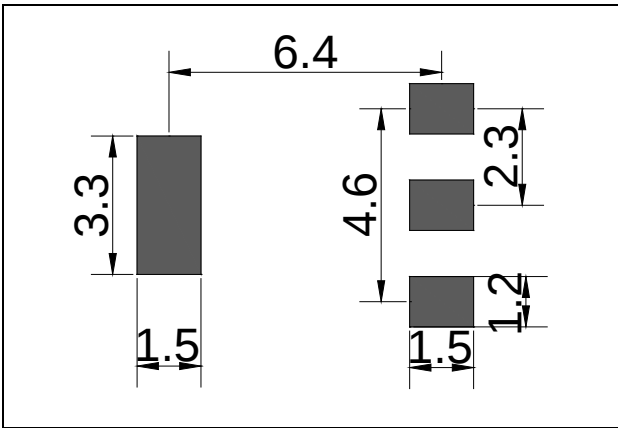
Date	Revision	Changes
Apr.13, 2023	A.1.0	Last updated
Oct.23, 2025	A.1.1	Revise PACKAGE MECHANICAL DATA

PACKAGE MECHANICAL DATA



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	1.50	1.60	1.80	0.059	0.063	0.071
A1	0.01	0.06	0.10	0.001	0.002	0.004
B	2.90	3.00	3.10	0.114	0.118	0.122
B1	0.60	0.70	0.80	0.024	0.028	0.031
C	0.22	0.26	0.32	0.009	0.010	0.013
D	6.30	6.50	6.70	0.248	0.256	0.264
E	3.30	3.50	3.70	0.130	0.138	0.146
F	4.40		4.80	0.173		0.189
F1	2.20		2.40	0.087		0.094
G	0.50		1.00	0.020		0.039
H	1.50	1.75	2.00	0.059	0.069	0.079
J	6.70	7.00	7.30	0.264	0.276	0.287
K	0.80		1.00	0.031		0.039
L	0.40		0.80	0.016		0.031
M	0.75		0.95	0.030		0.037

FOOTPRINT-SOT-223 (dimensions in mm)



Technical drawing of a 6-hole circular plate. The drawing includes a top view, a side view (B-B), and a cross-section view (A-A).

Top View: Shows a circular plate with six holes. The outer diameter is $\phi 120 \pm 0.2$. The inner diameter of the holes is $\phi 30 \pm 0.2$. The distance between the centers of adjacent holes is 2.3 ± 0.2 . The minimum distance from the hole center to the outer edge is $\phi_{\min} 12.8$. The plate has a thickness of 16.72 ± 0.3 .

Side View (B-B): Shows the profile of the plate. The total thickness is 16.72 ± 0.3 . The distance from the top surface to the center of the holes is 12.8 ± 0.5 . The distance from the bottom surface to the center of the holes is 100 ± 0.5 . The distance from the top surface to the bottom surface is 1.96 ± 0.2 . The distance from the center of the holes to the outer edge is 1.96 ± 0.2 . The distance from the center of the holes to the bottom surface is 12.8 ± 0.5 . The distance from the center of the holes to the top surface is 1.96 ± 0.2 .

Cross-section View (A-A): Shows the cross-section of the plate. The width of the plate is 6.8 . The distance from the center of the holes to the outer edge is $A0$.

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	-	-	12.30	-		0.482
E	1.65	1.75	1.85	0.065	0.069	0.073
F	5.45	5.50	5.55	0.215	0.217	0.219
D0	1.50	1.55	1.60	0.059	0.061	0.063
D1	1.50	-	-	0.059	-	-
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.95	2.00	2.05	0.077	0.079	0.081
10P0	39.80	40.00	40.20	1.567	1.575	1.583
A0	6.85	6.95	7.05	0.269	0.273	0.276
B0	7.15	7.25	7.35	0.280	0.284	0.288
K0	1.95	2.05	2.15	0.076	0.080	0.084
T	0.20	0.25	0.30	0.008	0.010	0.012

PACKAGE	OUTLINE	REEL (PCS)	PER CARTON (PCS)	TAPE & REEL
SOT-223	TAPING	4,000	40,000	13 inch

Information furnished in this document is believed to be accurate and reliable. However, Jiangsu JieJie Microelectronics Co., Ltd. assumes no responsibility for the consequences of use without consideration for such information nor use beyond it. Information mentioned in this document is subject to change without notice, apart from that when an agreement is signed, Jiangsu JieJie complies with the agreement.

Products and information provided in this document have no infringement of patents. Jiangsu JieJie assumes no responsibility for any infringement of other rights of third parties which may result from the use of such products and information. This document supersedes and replaces all information previously supplied.



is a registered trademark of Jiangsu JieJie Microelectronics Co., Ltd.

Copyright © 2025 Jiangsu JieJie Microelectronics Co., Ltd. All rights reserved.